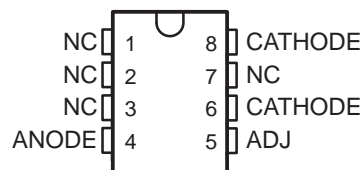


- Excellent Temperature Stability
- Initial Tolerance . . . 0.2% Max
- Dynamic Impedance . . . 0.6 Ω Max
- Wide Operating Current Range
- Directly Interchangeable With LM136
- Needs No Adjustment for Minimum Temperature Coefficient

D OR PW PACKAGE
(TOP VIEW)

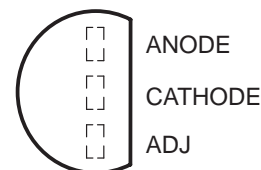


NC – No internal connection

description/ordering information

The LT1009 reference circuit is a precision-trimmed 2.5-V shunt regulator featuring low dynamic impedance and a wide operating current range. The maximum initial tolerance is ±5 mV in the LP package and ±10 mV in the D package. The reference tolerance is achieved by on-chip trimming, which minimizes the initial voltage tolerance and the temperature coefficient α_{VZ} .

LP PACKAGE
(TOP VIEW)



Although the LT1009 needs no adjustments, a third terminal (ADJ) allows the reference voltage to be adjusted ±5% to eliminate system errors. In many applications, the LT1009 can be used as a terminal-for-terminal replacement for the LM136-2.5, which eliminates the external trim network.

The LT1009 uses include 5-V system references, 8-bit analog-to-digital converter (ADC) and digital-to-analog converter (DAC) references, and power-supply monitors. The device also can be used in applications such as digital voltmeters and current-loop measurement and control systems.

The LT1009C is characterized for operation from 0°C to 70°C. The LT1009I is characterized for operation from –40°C to 85°C.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC (D)	Tube of 75	LT1009CD	1009C
		Reel of 2500	LT1009CDR	
	TO-226 / TO-92 (LP)	Bulk of 1000	LT1009CLP	LT1009C
		Ammo of 2000	LT1009CLPM	
		Reel of 2000	LT1009CLPR	
	TSSOP (PW)	Tube of 150	LT1009CPW	1009C
Reel of 2000		LT1009CPWR		
–40°C to 85°C	SOIC (D)	Tube of 75	LT1009ID	1009I
		Reel of 2500	LT1009IDR	
	TO-226 / TO-92 (LP)	Bulk of 1000	LT1009ILP	LT1009I
		Reel of 2000	LT1009ILPR	
	TSSOP (PW)	Tube of 150	LT1009IPW	1009I
		Reel of 2000	LT1009IPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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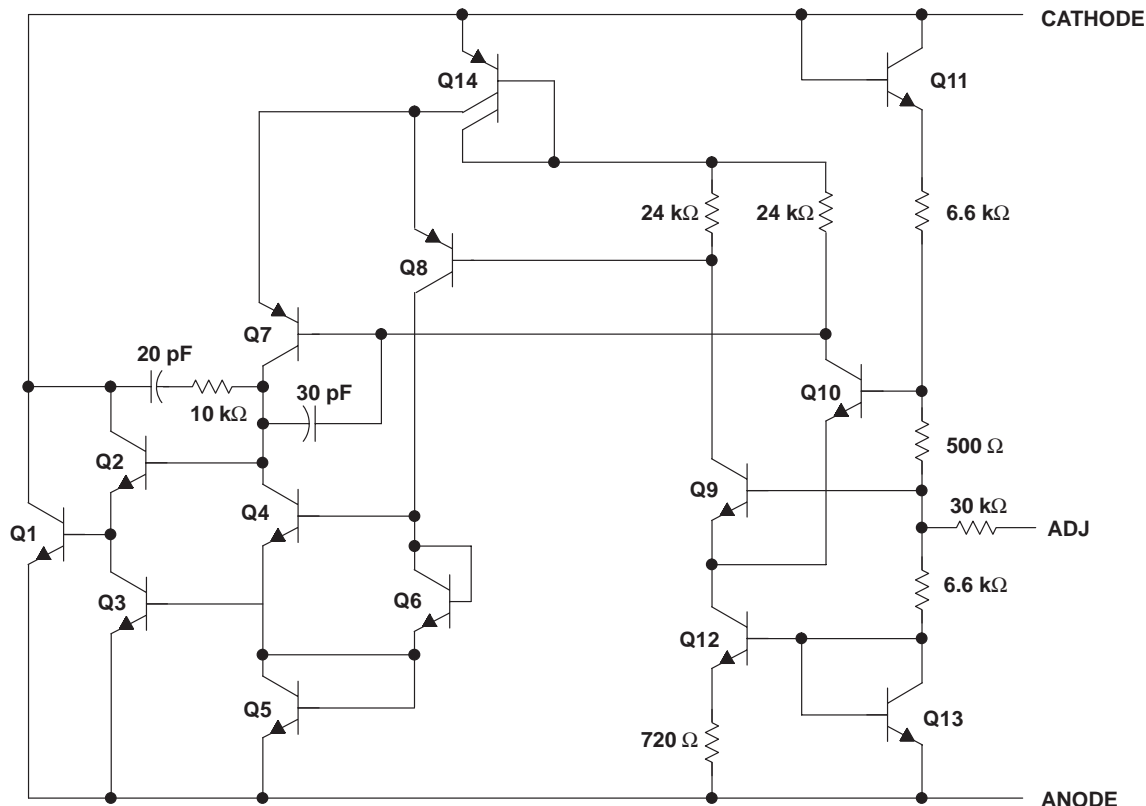
LT1009 2.5-V INTEGRATED REFERENCE CIRCUIT

SLVS013J – MAY 1987 – REVISED SEPTEMBER 2003

symbol



schematic



All component values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Reverse current, I_R	20 mA
Forward current, I_F	10 mA
Package thermal impedance, θ_{JA} , (see Notes 1 and 2): D package	97°C/W
LP package	140°C/W
PW package	149°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A) / \theta_{JA}$. Operation at the absolute maximum T_J of 150°C can impact reliability.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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LT1009

2.5-V INTEGRATED REFERENCE CIRCUIT

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recommended operating conditions

		MIN	MAX	UNIT	
T _A	Operating free-air temperature range	LT1009C	0	70	°C
		LT1009I	-40	85	

electrical characteristics at specified free-air temperature

PARAMETER	TEST CONDITIONS		T _A †	LT1009C			LT1009I			UNIT	
				MIN	TYP	MAX	MIN	TYP	MAX		
V _Z	Reference voltage	I _Z = 1 mA	25°C	D package	2.49	2.5	2.51	2.49	2.5	2.51	V
				LP package	2.495	2.5	2.505	2.495	2.5	2.505	
		Full range	D package	2.485		2.515	2.475		2.525		
			LP package	2.491		2.509	2.48		2.52		
V _F	Forward voltage	I _F = 2 mA	25°C	0.4		1	0.4		1	V	
	Adjustment range	I _Z = 1 mA, V _{ADJ} = GND to V _Z		25°C	125			125			mV
		I _Z = 1 mA, V _{ADJ} = 0.6 V to V _Z - 0.6 V			45			45			
ΔV _{Z(temp)}	Change in reference voltage with temperature		Full range		5			15			mV
					4			15			
α _{VZ}	Average temperature coefficient of reference voltage‡		0°C to 70°C	15			25			ppm/°C	
			-40°C to 85°C				20				
ΔV _Z	Change in reference voltage with current	I _Z = 400 μA to 10 mA	25°C	2.6			10			mV	
			Full range	12			10				
ΔV _Z /Δt	Long-term change in reference voltage	I _Z = 1 mA	25°C	20			20			ppm/khr	
z _Z	Reference impedance	I _Z = 1 mA	25°C	0.3			1			Ω	
			Full range	1.4			1.4				

† Full range is 0°C to 70°C for the LT1009C and -40°C to 85°C for the LT1009I.

‡ The average temperature coefficient of reference voltage is defined as the total change in reference voltage divided by the specified temperature range.



LT1009

2.5-V INTEGRATED REFERENCE CIRCUIT

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TYPICAL CHARACTERISTICS†

REFERENCE VOLTAGE
vs
FREE-AIR TEMPERATURE

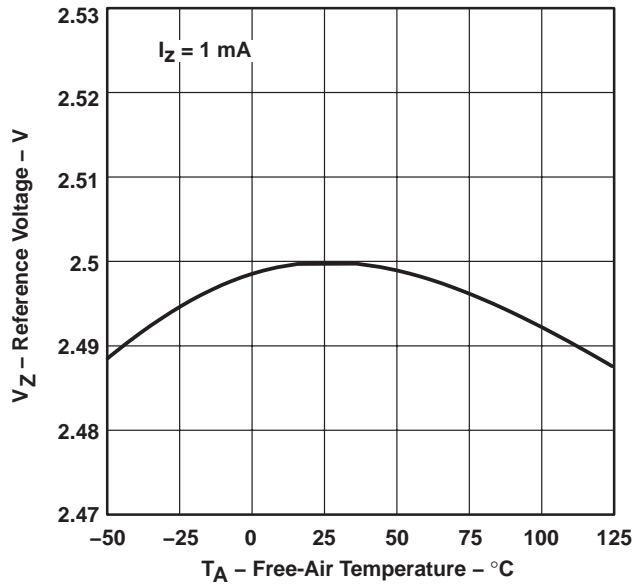


Figure 1

CHANGE IN REFERENCE VOLTAGE
vs
REFERENCE CURRENT

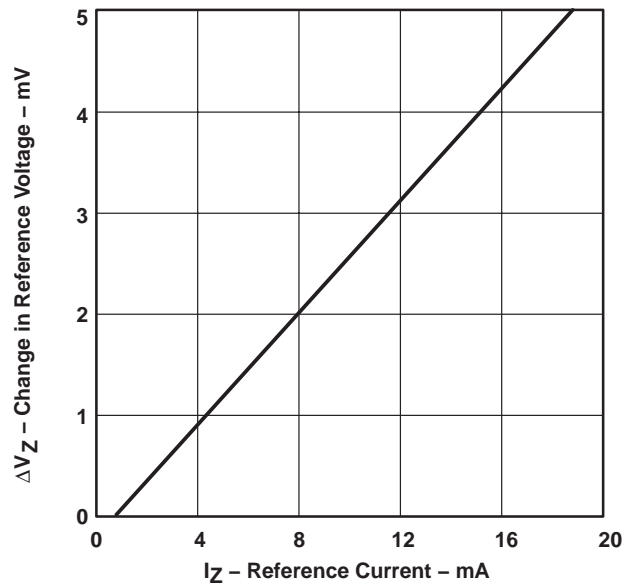


Figure 2

REVERSE CURRENT
vs
REVERSE VOLTAGE

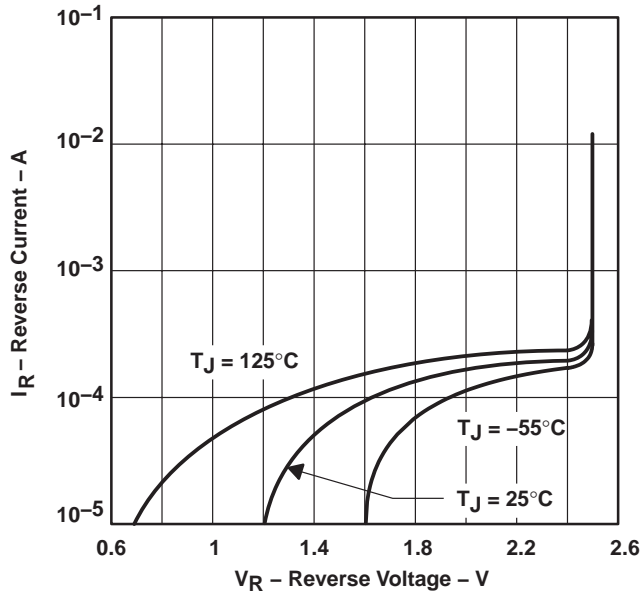


Figure 3

FORWARD VOLTAGE
vs
FORWARD CURRENT

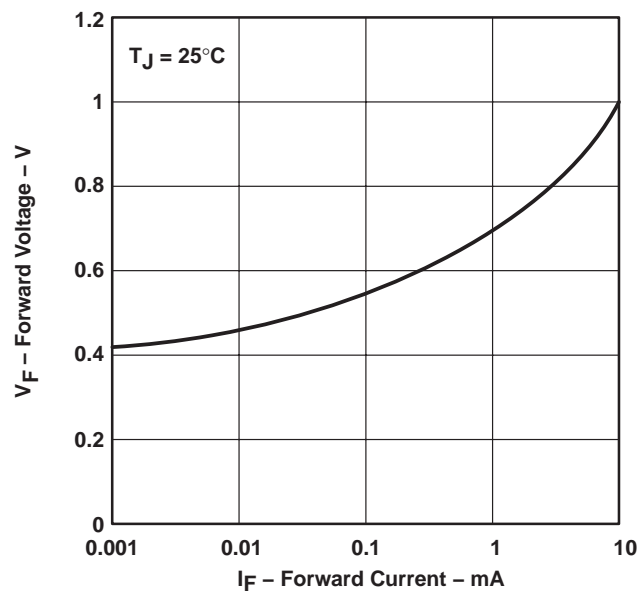


Figure 4

†Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

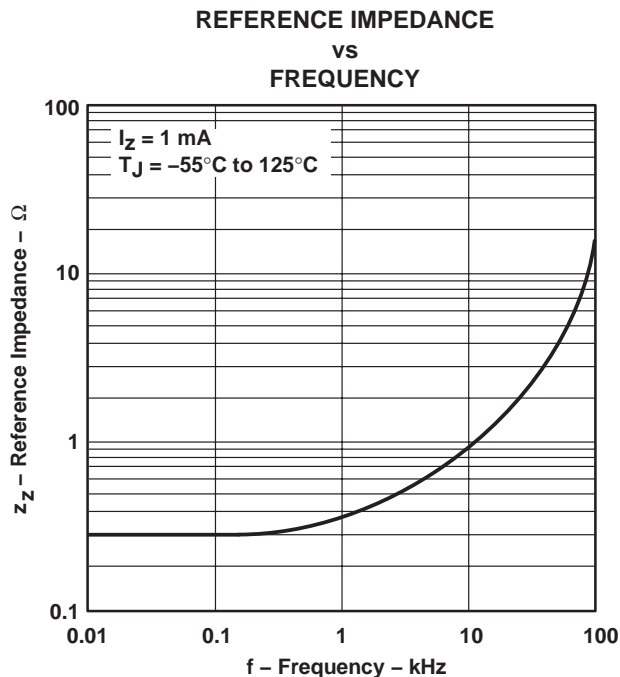


Figure 5

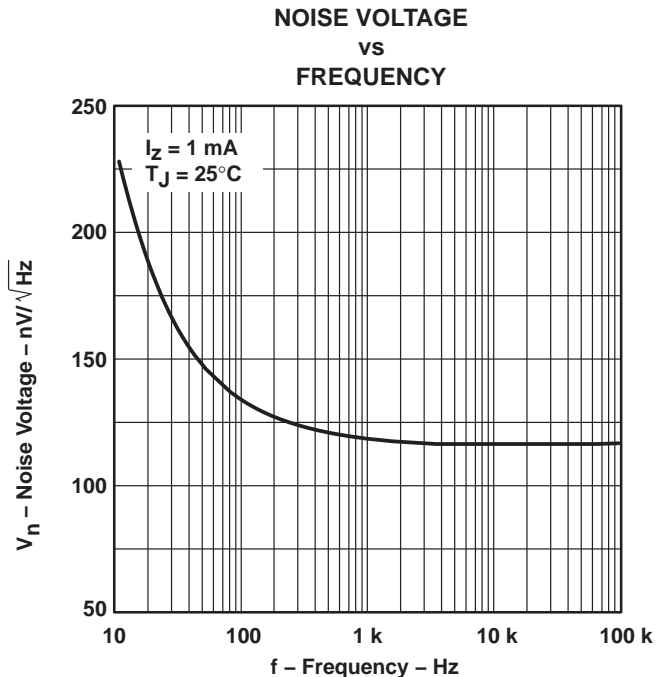


Figure 6

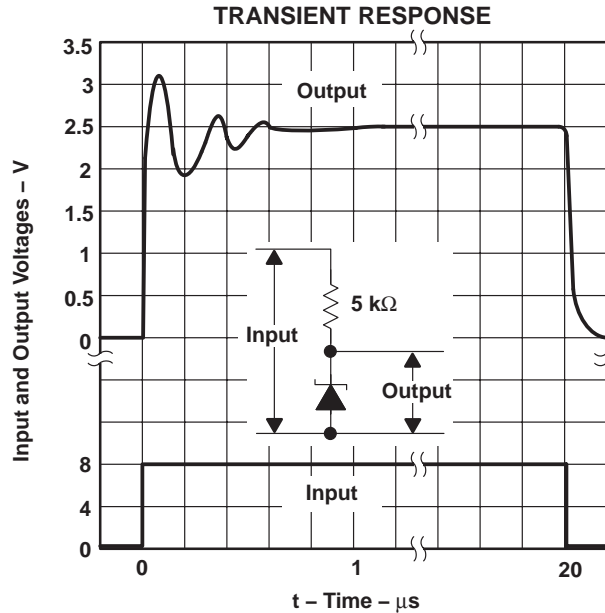
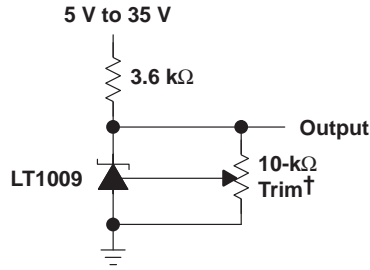


Figure 7

LT1009 2.5-V INTEGRATED REFERENCE CIRCUIT

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APPLICATION INFORMATION



†This does not affect temperature coefficient. It provides $\pm 5\%$ trim range.

Figure 8. 2.5-V Reference

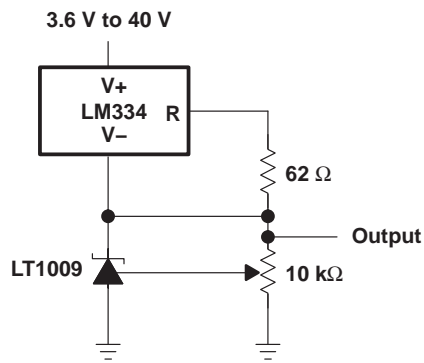


Figure 9. Adjustable Reference With Wide Supply Range

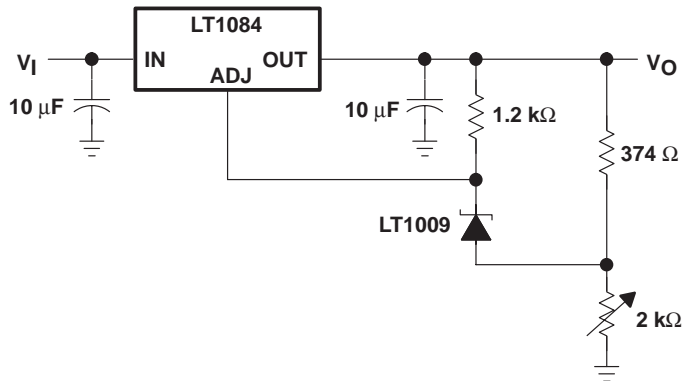


Figure 10. Power Regulator With Low Temperature Coefficient

APPLICATION INFORMATION

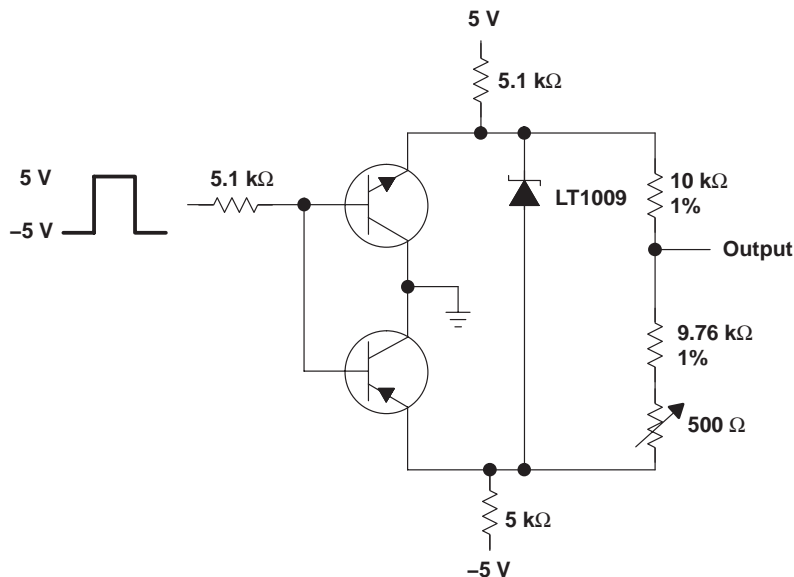


Figure 11. Switchable ± 1.25 -V Bipolar Reference

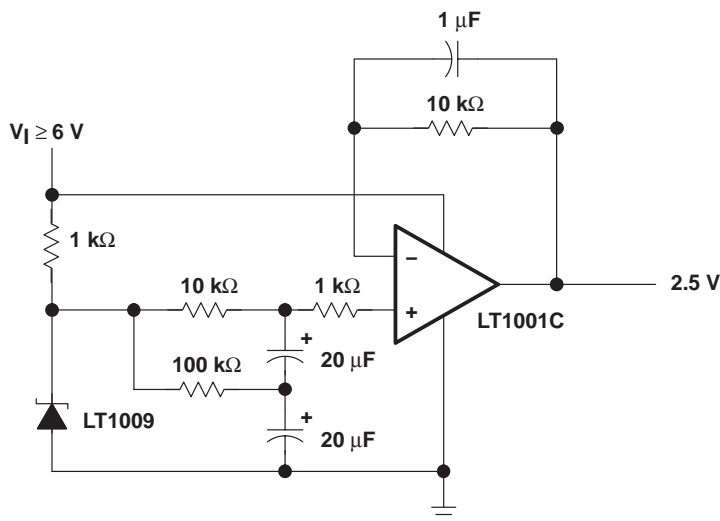


Figure 12. Low-Noise 2.5-V Buffered Reference

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LT1009CD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LT1009CDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LT1009CLP	ACTIVE	TO-92	LP	3	1000	None	CU SNPB	Level-NC-NC-NC
LT1009CLPM	ACTIVE	TO-92	LP	3	2000	None	CU SNPB	Level-NC-NC-NC
LT1009CLPR	ACTIVE	TO-92	LP	3	2000	None	CU SNPB	Level-NC-NC-NC
LT1009CPK	OBSOLETE	SOT-89	PK	3		None	Call TI	Call TI
LT1009CPW	ACTIVE	TSSOP	PW	8	150	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LT1009CPWR	ACTIVE	TSSOP	PW	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LT1009ID	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LT1009IDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
LT1009ILP	ACTIVE	TO-92	LP	3	1000	None	CU SNPB	Level-NC-NC-NC
LT1009ILPR	ACTIVE	TO-92	LP	3	2000	None	CU SNPB	Level-NC-NC-NC
LT1009IPW	ACTIVE	TSSOP	PW	8	150	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LT1009IPWR	ACTIVE	TSSOP	PW	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
LT1009QDR	OBSOLETE	SOIC	D	8		None	Call TI	Call TI
LT1009Y	OBSOLETE	XCEPT	Y	0		None	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

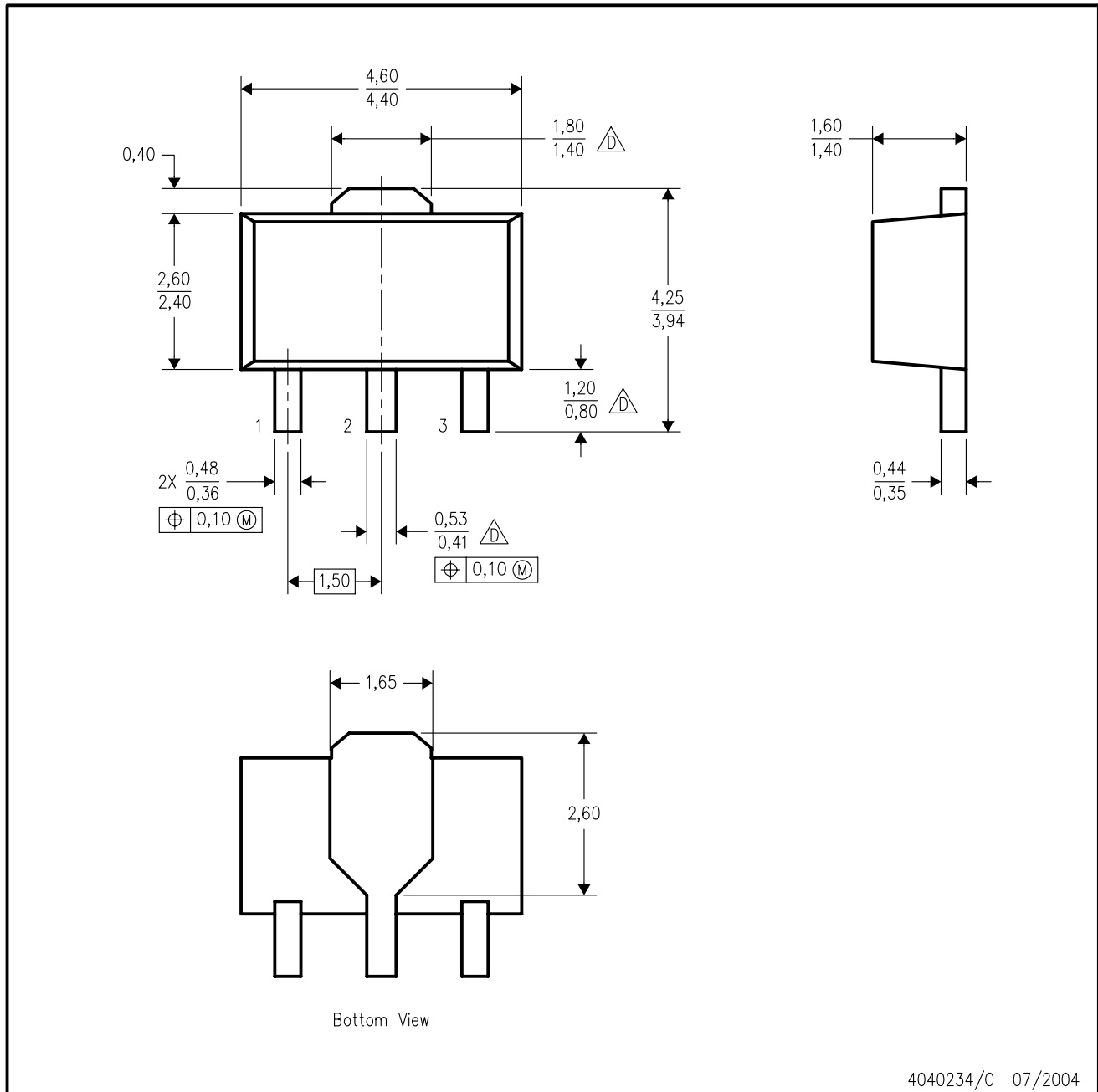
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PK (R-PSSO-F3)

PLASTIC SINGLE-IN-LINE PACKAGE



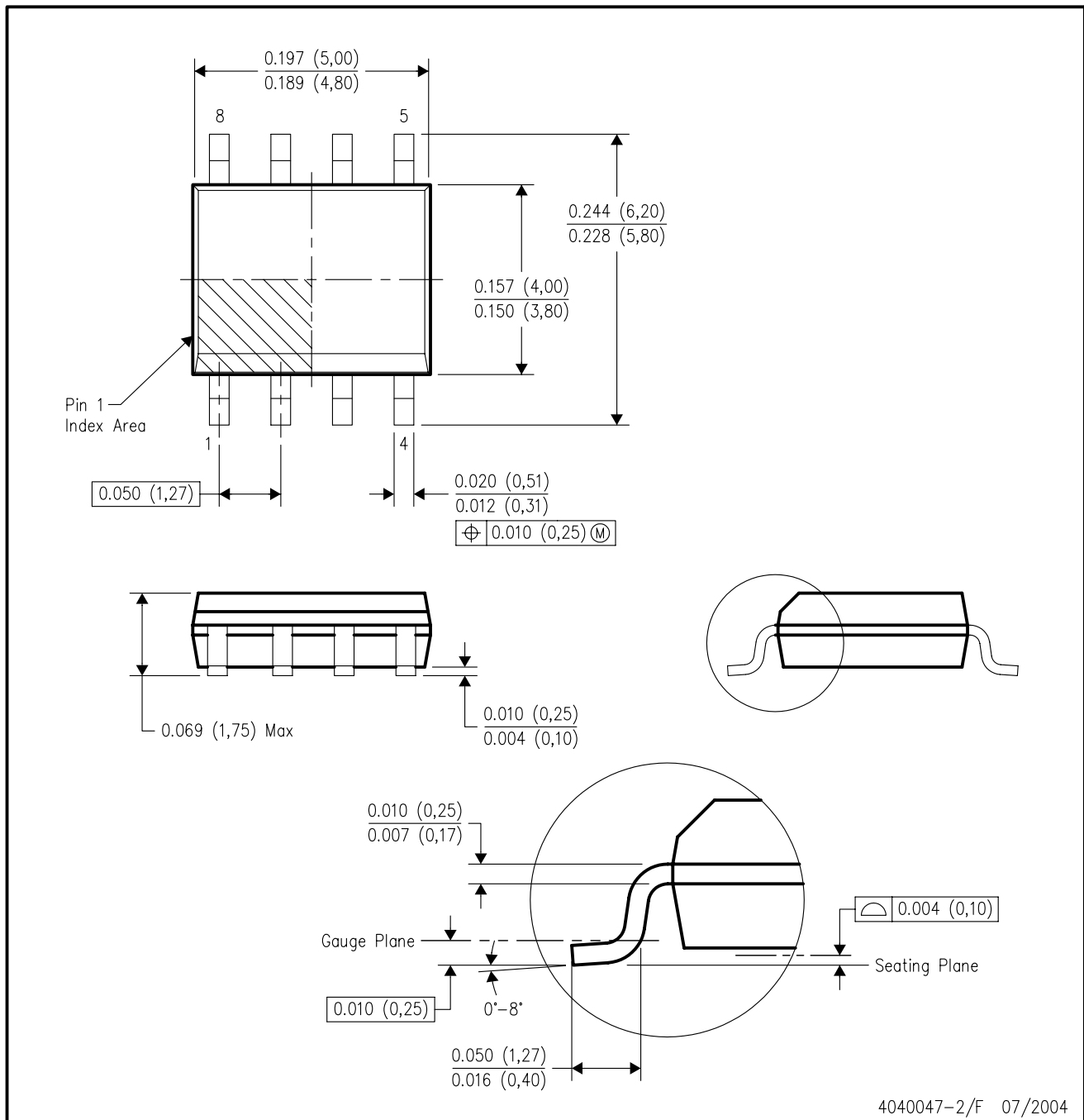
4040234/C 07/2004

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5-1994.
 - B. This drawing is subject to change without notice.
 - C. The center lead is in electrical contact with the tab.

\triangle Falls within JEDEC TO-243 variation AA, except minimum lead length, pin 2 minimum lead width, and minimum tab width.

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AA.

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



4040001-2/C 10/01



MECHANICAL DATA

MSOT002A – OCTOBER 1994 – REVISED NOVEMBER 2001

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Tape and Reel information for the Format Lead Option package.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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